



SC07 Rec'd PCT/PTO 10 OCT 2001

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Attn: OIPE

1746

Masatake NAKANO et al.

Application No.: 09/857,569

Docket No.: 109716

Filed: June 7, 2001

For: METHOD FOR PRODUCING BONDING WAFER AND BONDING WAFER

REQUEST FOR CORRECTION OF PALM RECORDS

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted.

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Date: October 10, 2001

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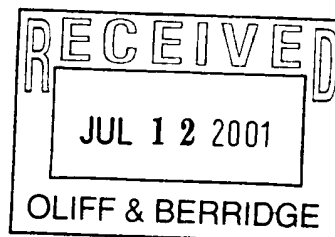
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/857,569	06/07/2001	1762	860	109715	5	1	1

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CONFIRMATION NO. 5019

FILING RECEIPT



OC000000006273118

Date Mailed: 07/09/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

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Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/06795 09/29/2000

Foreign Applications

JAPAN 11/292130 10/14/1999

Projected Publication Date: N/A

Non-Publication Request: No

Early Publication Request: No

Title

Method for producing bonded wafer and bonded wafer

Preliminary Class

427